05-07-2004

PTO-1595 R' SHEET U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

102739613

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1 Name of conveying party(ies):

KENG-CHU LIN, TIEN-I BAO, SYUN-MING JANG

4-30-04

2 Name and address of receiving party(ies):

Taiwan Semiconductor Manufacturing Co. Ltd.
No. 8. Li-Hsin Rd. 6
Science-Based Industrial Park
Hsin-Chu, Taiwan, R.O.C.

22141 U.S. PTO
10/836297
043004

3 Nature of conveyance:

■ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other:
Execution Date Dec. 31, 2003

Additional name(s) & address(es) attached ☐ Yes ☒ No

10836297

4 Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: 12/31/03

A. Patent Application No(s).	B. Patent No(s)

Additional numbers attached? ☐ Yes ☒ No

5 Name and address of party to whom correspondence concerning document should be mailed:

RANDY W. TUNG
Tung & Associates
838 W. Long Lake Road
Suite 120
Bloomfield Hills, Michigan 48302

6 Total number of applications and patents involved: 1

7 Total fee (37 CFR 3.41) $40.00

☐ Enclosed
☒ **Authorized to charge credit card (w/filing fee)**

8 Deposit Account Number:
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9 Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Randy W. Tung
Name of Person Signing
Registration No. 31,311

Signature

Apr 30/04
Date

Total number of pages including cover sheet, attachments, and document : 3

67,200-1237

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

05/05/2004 WASFAW1 00000025 10836297
04 FC:8021 40.00 OP

67,200-1237
2003-1067

ASSIGNMENT

WHEREAS, we, KENG-CHU LIN, TIEN-I BAO, and SYUN-MING JANG, have invented certain improvements in

METHOD OF FORMING CAPPING LAYER OVER CU INTERCONNECTS TO IMPROVE ELECTRICAL PERFORMANCE

for which we are about to make application for Letters Patent of the United States; and

WHEREAS, TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD. of No. 121, Park Avenue 3, Science-Based Industrial Park, Hsin-Chu, Taiwan, R.O.C, is desirous of acquiring the entire right, title and interest in and to said invention;

NOW, THEREFORE, in consideration of One Dollar ($1.00) and other good and valuable consideration, the receipt of which is hereby acknowledged, we, KENG-CHU LIN, TIEN-I BAO, and SYUN-MING JANG, by these presents, do hereby sell, assign and transfer unto the said corporation and its assigns, for the territory of the United States of America and all foreign countries, the entire right, title and interest, including all priority rights under the International Convention associated with each country of the Union, in and to said invention as described in the patent application executed by us on the 31th day of December, 2003, preparatory to obtaining Letters Patent of the United States thereon, and in and to said application and any Letters Patent that may be granted in pursuance of said application and any divisional, continuation or continuation-in-part application thereof, and in and to any reissue of any such patent, and in and to any patent applications which may be filed on said invention in countries foreign to the United States and any Letters Patent granted thereon.

We further authorize said corporation to apply for foreign patents on said invention in its own name or through its designees, including subsidiaries, related companies or assignees, under the International Convention or otherwise, and we further agree to execute all papers, including those required for the United States and foreign applications, and to perform such other proper acts as said corporation or its designees the rights herein assigned.

KENG-CHU LIN

Tien-I Bao
TIEN-I BAO

SYUN-MING JANG

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